Specification of Thermoelectric Module

TEFC1-00709

Description

The 7 couples, 3.2 mm × 3.2mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 74 ºC, designed for superior cooling and heating up to 100/200 ºC applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

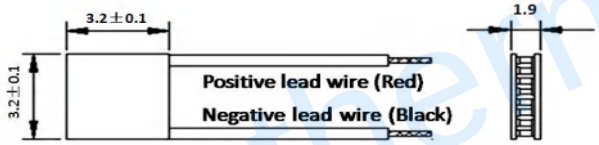
Application

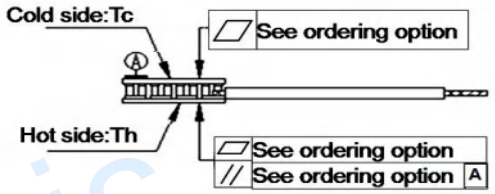
- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (ºC)	27	50	Hot side temperature at environment: dry air, N_2
DT_{max} (ºC)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U_{max} (Voltage)	0.92	0.96	Voltage applied to the module at DT_{max}
I_{max} (Amps)	0.9	0.9	DC current through the modules at DT_{max}
Q_{Cmax} (Watts)	0.52	0.57	Cooling capacity at cold side of the module under DT=0 ºC
AC resistance (Ohms)	0.77	0.79	The module resistance is tested under AC
Tolerance (%)	10%		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters





Manufacturing Options

A. Solder:

1. T100: BiSn (Tmelt=138ºC)
2. T200: CuAgSn (Tmelt = 217°C)
3. T240: SbSn (Tmelt = 240°C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

C. Ceramics:

1. Alumina (Al_2O_3, white 96%)
2. Aluminum Nitride (AlN)

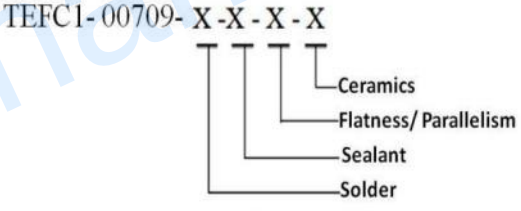
D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

Ordering Option

Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:1.9± 0.1	0: 0.03/0.03	Connect the Pin
TF	1:1.9 ± 0.03	1: 0.015/0.015	Connect the Pin
Eg. TF11: Thickness 1.9± 0.03 (mm) and Flatness 0.015/0.015(mm)			

Naming for the Module



TEFC1-00709–T100-NS –TF11-AlO

T100: BiSn (Tmelt=138°C)

NS: No sealing

AlO: Alumina, white 96%

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Sub-assembly Overview

Practical Application

The TEFC module is mounted to a header for cooling in photonic application.

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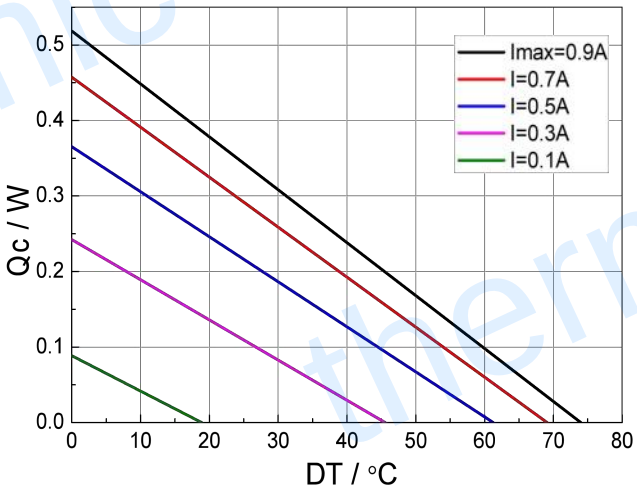
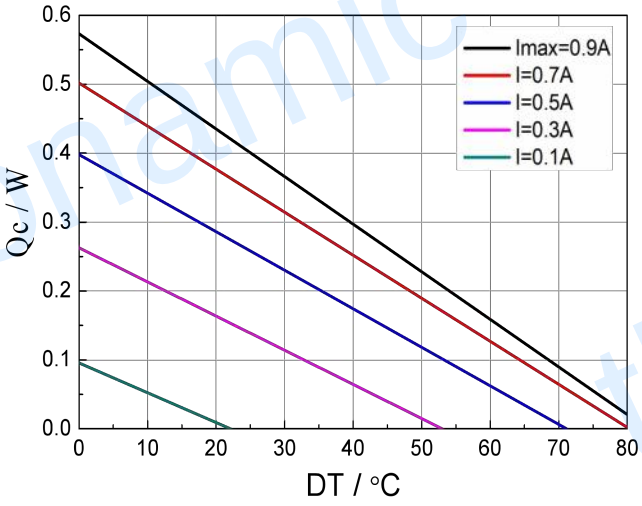
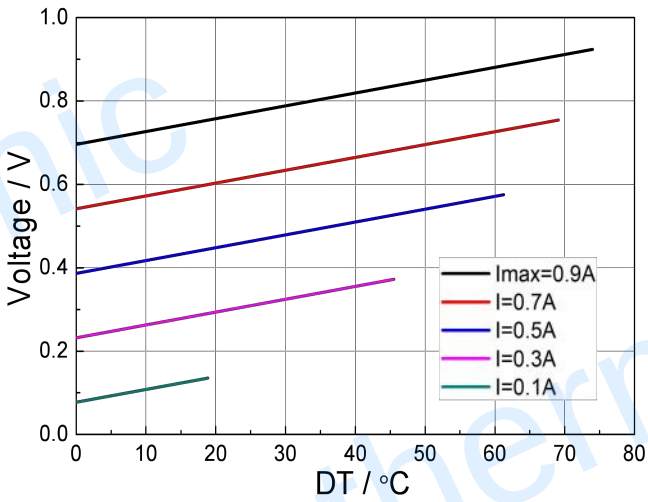
Performance Curves at Th=27 ºC

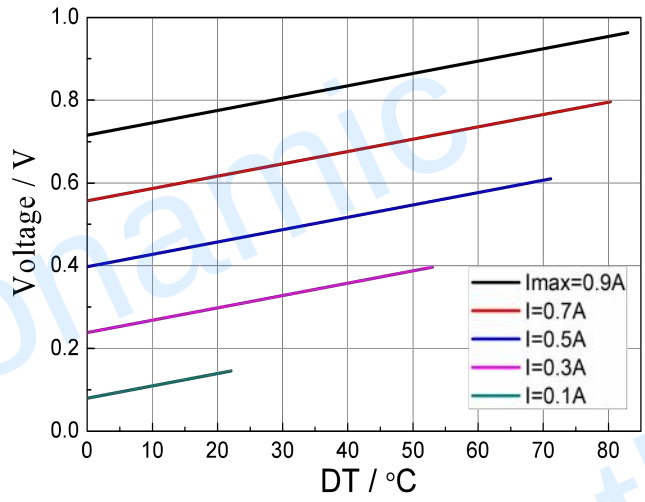


Performance Curves at Th=50 ºC



Standard Performance Graph Qc= f(DT)





Standard Performance Graph V= f(DT)

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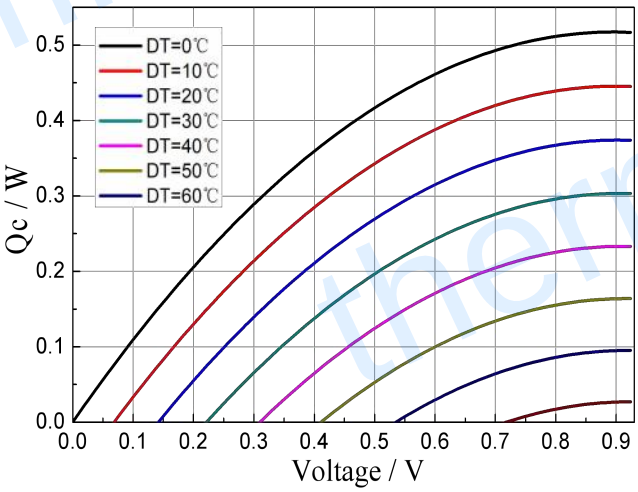
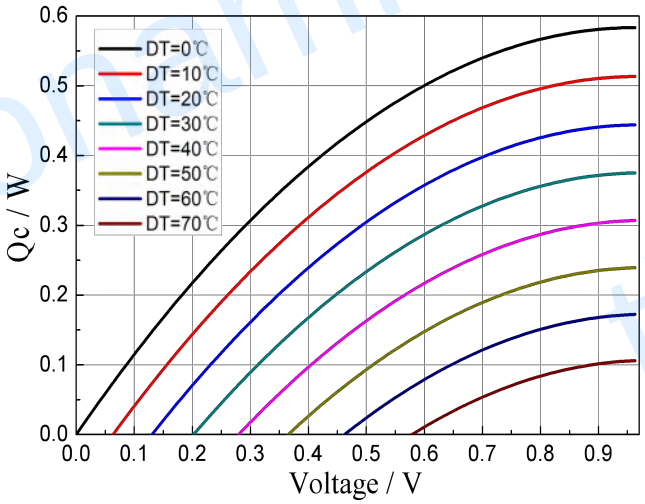
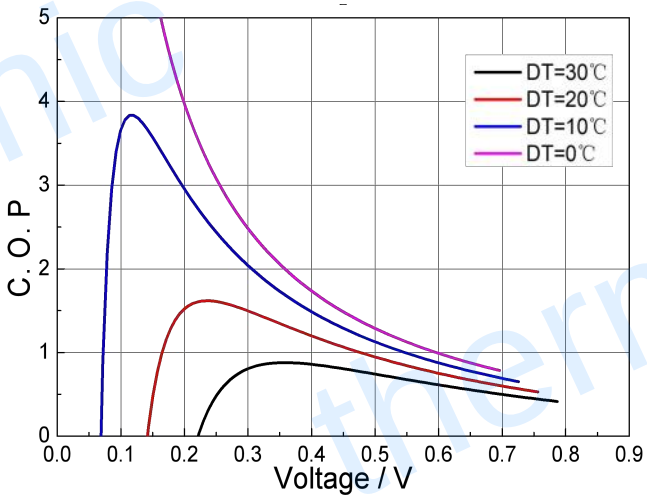
Performance Curves at Th=27 ºC

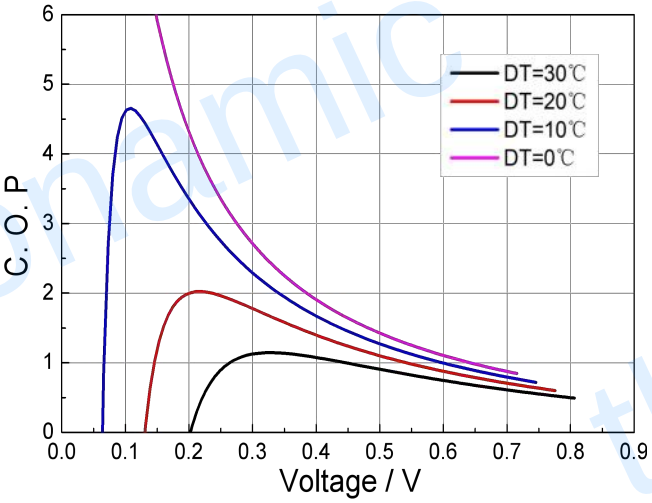


Performance Curves at Th=50 ºC

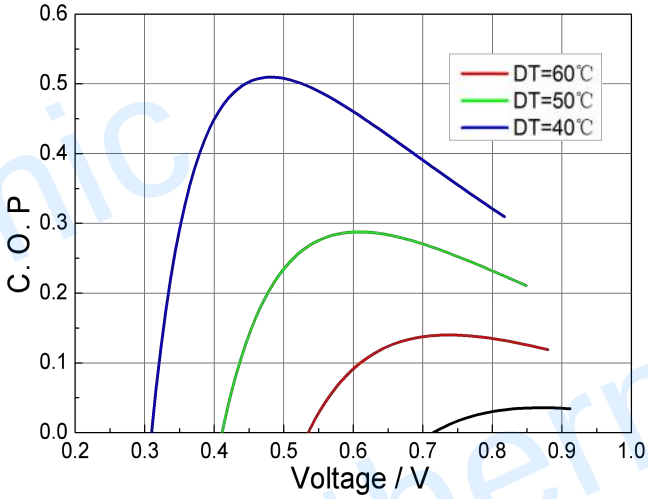


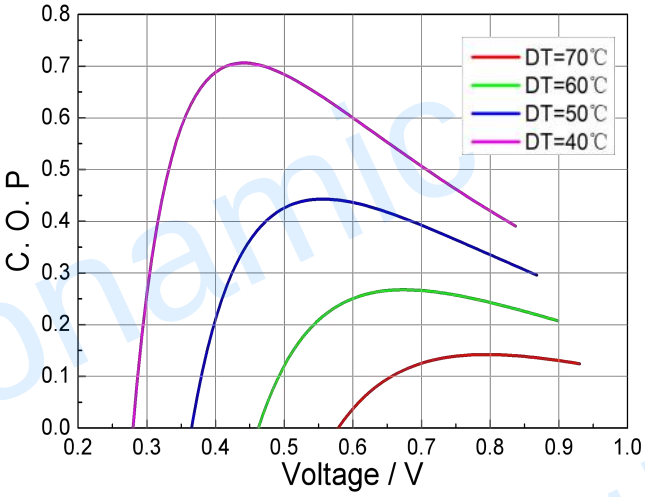
Standard Performance Graph Qc= f(V)





Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 ˚C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 ˚C

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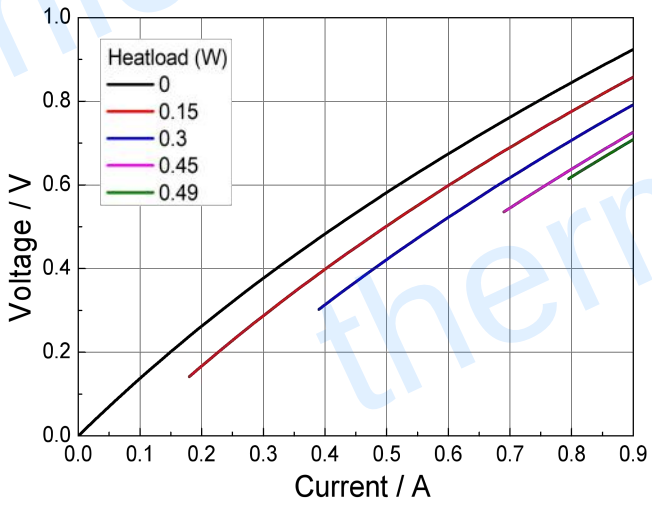
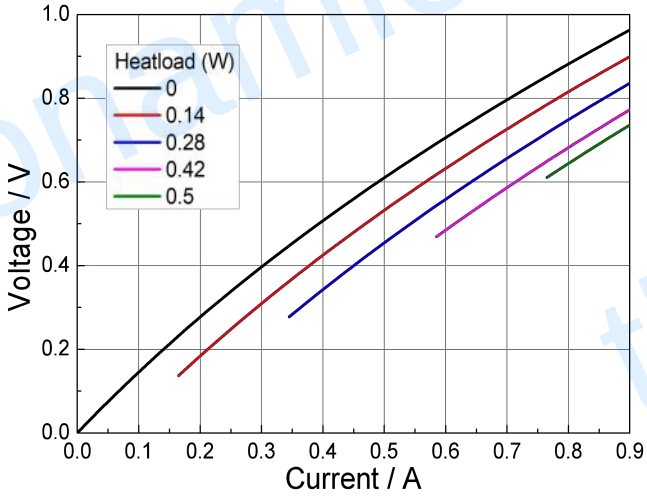
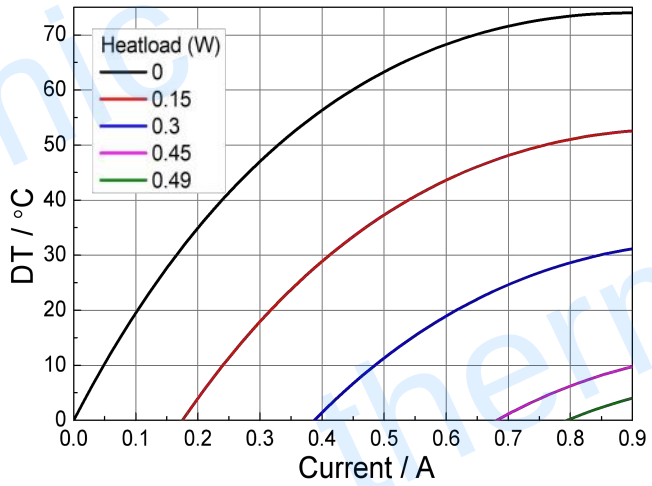
Performance Curves at Th=27 ºC

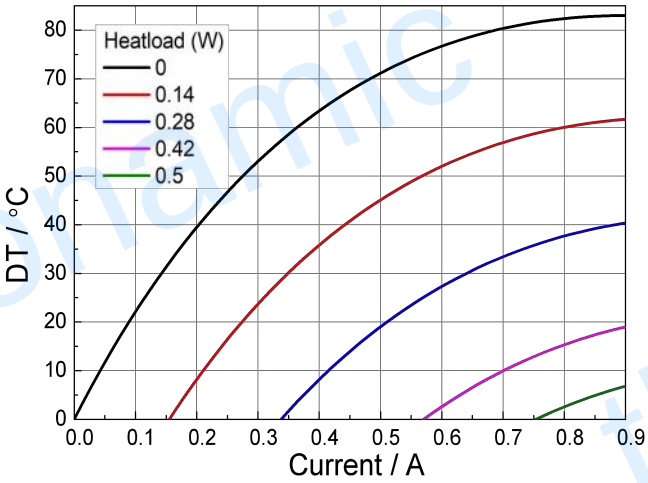


Performance Curves at Th=50 ºC



Standard Performance Graph V= f(I)





Standard Performance Graph ΔT= f(I)

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Caution

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.

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